AMENDMENTS TO THE SPECIFICATION

In the Specification:

Please replace the paragraph beginning on page 6, line 27 as follows:

The main body 1 may be formed by injection molding a plastic resin such as poly carbonate(PC), PCABS, PPA, nylon, polyethyleneterephthalate(PET), polybutyleneterephthalate(PBT), or amodel. The main body 1 may be formed in a single body along with at least a septum 3 ~~which~~ that electrically isolates the at least two heat sinks 7. In addition, the main body 1 may be attached to the lead terminals 5 and the at least two heat sinks 7 using an insert-molding technique.

Please replace the paragraph beginning on page 7, line 1 as follows:

The at least two heat sinks 7 may be slugs~~, and~~ with each heat sink having an upper surface for mounting LED dies. Each of the at least two heat sinks 7 may also have a reflective surface 9 extended from the upper surface thereof. The at least two heat sinks 7 having the reflective surface 9 are appropriately arranged to gather the light emitted from the LED dies efficiently. The at least two heat sinks 7 are formed of electrically and thermally conductive materials. For example, the at least two heat sinks 7 may be formed of copper(Cu), gold, silver(Ag), silicon carbide(SiC) or aluminum(Al). Since each of the at least two heat sinks 7 is conductive, each of the heat sinks 7 may be used as an electrode of the LED die and be electrically connected to the lead terminals 5 through bonding wires. The at least two heat sinks 7 are separated from each other. The at least two heat sinks 7 may be separated by ~~the~~ at least a septum 3 formed in a single body along with the main body 1. Although the two heat sinks 7a, 7b separated from each other are shown in FIG. 2 to FIG. 4, ~~the~~ there may be more than

two heat sinks 7 ~~may include much more number of heat sinks~~. In addition, the lower surface of each of the heat sinks 7 may have a relatively wide width compared with the upper surface thereof to promote thermal relief.

Please replace the paragraph beginning on page 7, line 27 as follows:

Referring to FIG. 5, LED dies 13 are mounted on each of the at least two heat sinks 7a, 7b. Each of the LED dies 13 is electrically and directly connected to the heat sinks 7 via a surface of the LED die. That is, the surface of each of the LED dies 13 is contacted with the upper surface of the heat sink 7 without any submount. The number of the LED dies attached on each of the at least two heat sinks 7 may be varied with a desired purpose. And, various kinds of the LED dies 13 may be selected according to the desired purpose. However, it is preferable that the LED dies 13 having the same structure are mounted in one package to make sure of uniformity of emitted light and simplify fabrication processes of the LED package. Also, the LED dies 13 may be arranged symmetrically with each other to make sure of uniformity of emitted light.

Please replace the paragraph beginning on page 8, line 18 as follows:

Meantime, a lens 15 is attached to the main body 1 to enclose the LED dies 13. The lens 15 may have a variety of shapes according to its applications. Further, the lens 15 may include an optically transparent material directly contacted with the LED dies 13. The optically transparent material may be [[an]] a transparent epoxy or silicone, and contain an additive such as [[an]] a diffusing material, [[an]] a fluorescent material and so on. The diffusing material prevents the bonding wires 11 and LED dies 13 from appearing on the outside, while the fluorescent material converts a wavelength of light

emitted from the LED dies 13. And the fluorescent material may be distributed directly on the LED dies 13. The desired wavelengths of light [[is]] are emitted to the outside by appropriately selecting the fluorescent material. For example, the fluorescent material may be a material including at least one element selected from the group consisting of Ca, Sr, Ba and O, and at least one element selected from the group consisting of Al, O and Si, and activated by an element (Eu) of cerium group.

Please replace the paragraph beginning on page 9, line 3 as follows:

FIG. 6 is a perspective view illustrating an LED package 21 according to the second embodiment of the present invention. And FIG. 7 and FIG. 8 are an exploded perspective view of ~~the~~ FIG. 6 and a cross sectional view of FIG. 6 without a lens, respectively. Also, FIG. 9 is a bottom perspective view illustrating a main body of FIG. 6. In the second embodiment, it is described in detail the LED package 21 having three heat sinks and four lead terminals. However, the numbers of the heat sinks and the lead terminals are not limited by the above. That is, it is possible for the LED package 21 to have two heat sinks and three lead terminals, and also for the LED package 21 to have more than two heat sinks and three lead terminals ~~may have much more numbers of heat sinks and lead terminals~~.

Please replace the paragraph beginning on page 9, line 14 as follows:

The main body 31 may be formed by injection molding a plastic resin, as described referring to FIG. 2 to FIG. 4. The main body 31 is formed in a single body along with septa 35 ~~which~~ that electrically isolates the heat sinks 41. In addition, the main body 31 is attached to the lead terminals 51 and the heat sinks 41 using an insert-molding technique. The main body 31 may have heat-sink receiving recesses 33, and

the heat-sink receiving recesses 33 may be separated by the septa 35. The receiving recesses 33 may be holes passing through the main body 31, as shown in the drawings.

Please replace the paragraph beginning on page 9, line 21 as follows:

Lead-terminal receiving grooves 37 may be placed onto an upper surface of the main body 31. The lead-terminal receiving grooves 37 may be arranged along the circumference direction of the main body 31, as shown in the drawings. The lead terminals 51 are mounted to the lead-terminal receiving grooves 37, respectively. Lead terminal holes 39 passing through the side wall of the main body 31 may be connected to the lead-terminal receiving grooves 37, respectively. The lead terminals 51 mounted to the lead-terminal receiving grooves 37 project outside through the lead-terminal holes 39.

Please replace the paragraph beginning on page 10, line 24 as follows:

The LED dies 47a, 47b and 47c are mounted on the heat sinks 41. As shown in FIG. 6 to FIG. 8, the LED dies 47a, 47b and 47c may be one by one mounted on the heat sinks 41. However, the number of the LED dies mounted on each of the heat sinks 41 is not limited by the above, and ~~much more number of the~~ multiple LED dies may be mounted on each of the heat sinks 41. The LED dies 47a, 47b and 47c include LED dies ~~emitting the~~ that emit different wavelengths of light from each other. That is, the LED dies 47a, 47b and 47c may include a first group emitting a first wavelength of light, a second group emitting a second wavelength of light and a third group emitting a third wavelength of light. The first, second and third wavelengths may be red, green and blue wavelengths, respectively. In addition, the first, second and third groups may be mounted on the heat sinks 41, respectively. For the convenience of description, the heat

sinks 41 on which the first, second and third groups are mounted, are defined as a first heat sink, a second heat sink and a third heat sink, respectively. The LED package embodying polychromatic light using the LED dies 47a, 47b and 47c, [[are]] is described referring to FIG. 10.

Please replace the paragraph beginning on page 11, line 9 as follows:

Referring to FIG. 10, the heat sinks 41, the lead terminals 51 and the LED dies 47a, 47b and 47c are connected by bonding wires 49. In this case, the first, second and third heat sinks 41 are electrically connected to the lead terminals 51, respectively. For convenience of description, the lead terminals 51 connected to the first, second and third heat sinks 41 are defined as a first lead terminal, a second lead terminal and a third lead terminal, respectively. Meantime, the lead terminals 51 include a common lead terminal electrically connected to all of the first, second and third heat sinks 41, in addition to the first, second and third lead terminals. More concretely, a negative common lead terminal (-) is connected to the first, second and third heat sinks 41 through the bonding wires 49, while positive lead terminals (+) are connected to the respective LED dies 47a, 47b and 47c through the bonding wires 49, as shown in FIG. 10. Thus, the LED dies mounted on one heat sink may be connected to a power source different from that which is connected to the LED dies mounted on another heat sink. That is, three power sources may be connected between the common lead terminal and each of the first, second and third lead terminals. As a result, polychromatic lights from the LED package 21 may be embodied by controlling ON/OFF of the power sources. For example, when a power source between the first lead terminal and the common lead terminal is turned on, and the other power sources are turned off, the first group of light can be emitted. If the three power sources are turned on, all of the first, second and third groups of light can be

emitted to embody white light. Meantime, ~~much more number of~~ many colors can be embodied by controlling the amount of electric power supplied to the respective LED dies 47a, 47b and 47c, instead of controlling ON/OFF of the power sources. The amount of electric power supplied to the respective LED dies 47a, 47b and 47c can be controlled by controlling the amount of ~~currents or voltages~~ current or voltage supplied to the respective LED dies. A controller (not shown) may be connected to the LED package 21 to control ON/OFF of the power sources or control the electric power. Meantime, the heat sinks 41, the lead terminals 51 and the LED dies 47a, 47b and 47c can be connected by the bonding wires 49 in various connecting manners.